

N-Channel Enhancement Mode Power MOSFET

Description

The MSF6N60 is a N-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The ITO-220AB package is universally preferred for all commercial-industrial applications

Features

- Low On Resistance •
- Simple Drive Requirement
- Low Gate Charge •
- Fast Switching Characteristic
- RoHS compliant package ٠

Application

- **Open Framed Power Supply**
- Adapter •
- STB •

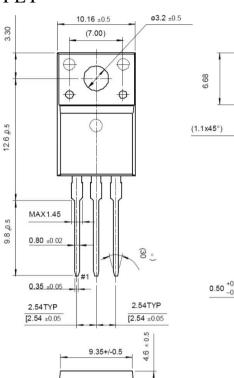
Package type : ITO220-AB

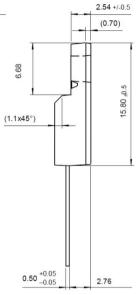
Packing & Order Information

50/Tube ; 1,000/Box



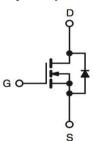








Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings						
Symbol	Parameter	Value	Unit			
Vdss	Drain-Source Voltage	600	V			
V _{GS}	Gate-Source Voltage	±30	V			
ID	Drain Current -Continuous (TC=25°C)	4.5	А			
	Drain Current -Continuous (TC=100°C)	2.6	Α			
IDM	Drain Current Pulsed	18	А			
IAR	Avalanche Current	4.5	А			
E _{AS}	Single Pulsed Avalanche Energy	58.6	mJ			
Ear	Repetitive Avalanche Energy	10	mJ			
dv/dt	Peak Diode Recovery dv/dt	4.5	V/ns			



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Absolute Maximum Ratings						
Symbol	Parameter	Value Unit				
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C			
TPKG	PKG Maximum Temperature for Soldering @ Package Body for 10 seconds		°C			
PD	Total Power Dissipation (TC=25°C)	33	W			
	Derating Factor above 25 °C	0.26	W/°C			
T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C			
TJ	Storage Temperature	150	°C			

Notes;

1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. I_{AS}=4.5A, V_{DD}=50V, L=7mH, V_G=10V, Starting T_J =25°C

3. I_{SD} \leq 4.5A, di/dt \leq 100A/µs,V_{DD} \leq BV_{DSS}, Starting T_J=25°C

Thermal Characteristics						
Symbol	ol Parameter Max. Units					
Røjc	Thermal Resistance, Junction-to-Case	3.75	°C/W			
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5				

Static Characteristics						
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0~V$, $I_{D}\text{=}250\mu\text{A}$	600			v
ΔBV_{DSS}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to $25^{\circ}C$		0.6		V/°C
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250 \mu A$	2.0		4.0	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 480 \text{ V}, T_C = 125^{\circ}C$			1 10	μA
I _{GSS}	Gate-Body Leakage Forward	$V_{GS} = \pm 30$			±100	nA
Rds(ON)	Static Drain-Source On-Resistance	$V_{GS} = 10 V, I_D = 3.0 A$		1.8	2.3	Ω

Dynamic Characteristics							
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units	
td(on)	Turn-On Time	$\label{eq:VDS} \begin{split} V_{DS} &= 300 \ V, \ I_D = 4.5 \ A, \\ R_G &= 10 \ \Omega \ , \ V_{GS} = 10 \ V \end{split}$		9.6		ns	
t _r	Turn-On Time			12.2		ns	
t _{d(off)}	Turn-Off Delay Time			22.3		ns	
tf	Turn-Off Fall Time			14.8		ns	



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Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
Q_g	Total Gate Charge	$V_{DS} = 300 \text{ V}, I_D = 4.5 \text{ A},$ $V_{GS} = 10 \text{ V}$		16		nC
Q _{gs}	Gate-Source Charge			3.3		nC
Q_{gd}	Gate-Drain Charge			6.2		nC
CISS	Input Capacitance	$V_{DS} = 25 V, V_{GS} = 0 V,$ f = 1.0MHz		700		pF
Coss	Output Capacitance			86		pF
C _{RSS}	Reverse Transfer Capacitance			20		pF

Source-Drain Diode							
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units	
Is		$V_D = V_G = 0$			4.5	•	
Ism		$V_{\rm S} = 1.3 {\rm V}$			18	A	
Vsd		$I_S=4.5~A~,~V_{GS}=0~V$			1.5	v	
t _{rr}		$I_F = 4.5 A, V_{GS} = 0 V$		320		ns	
Qrr		diF/dt=100A/µs		2.7		μC	

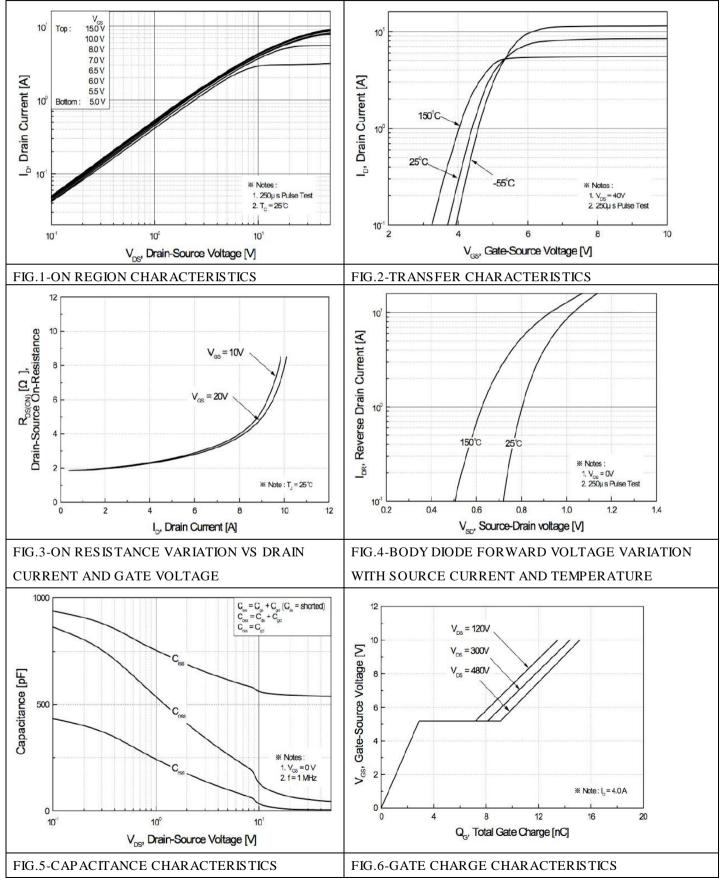
Notes;

1. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%



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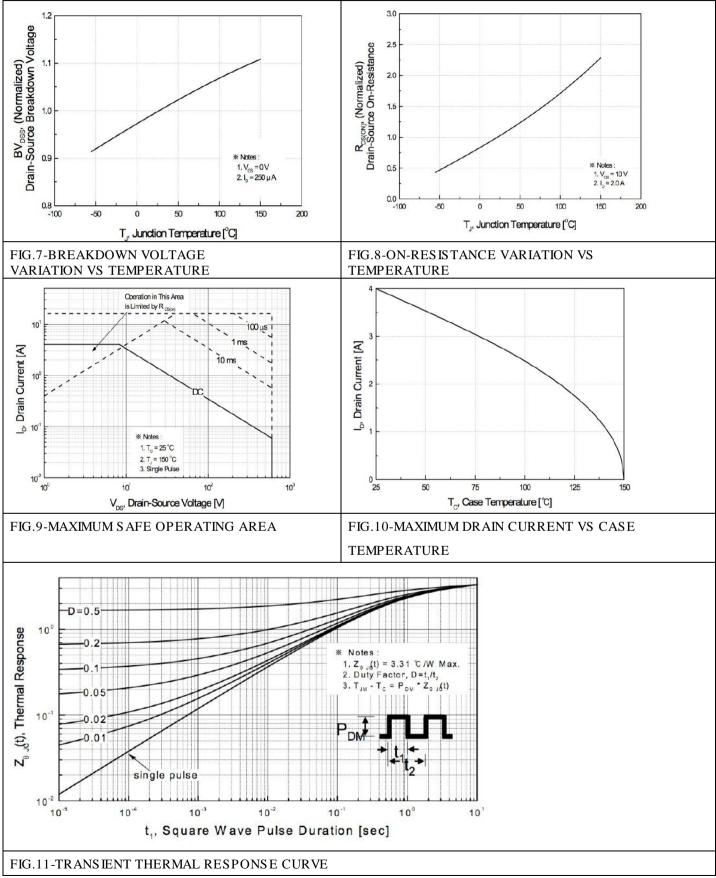
Characteristics Curve





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Characteristics Curve





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